

## Product Summary

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
-40V	13mΩ @ V <sub>GS</sub> = -10V	-10.3A
	18mΩ @ V <sub>GS</sub> = -4.5V	-8.8A

## Features and Benefits

- Low R<sub>DS(ON)</sub> – ensures on state losses are minimized.
- Small form factor thermally efficient package enables higher density end products.
- Occupies 33% of the board area occupied by SO-8, enabling smaller end product.
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Description and Applications

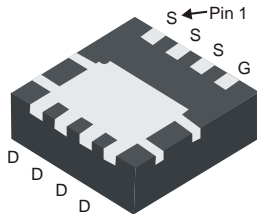
This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

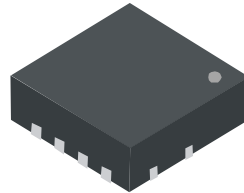
## Mechanical Data

- Case: POWERDI®3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208③
- Weight: 0.072 grams (Approximate)

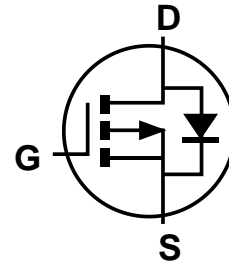
POWERDI®3333-8



Bottom View



Top View



Equivalent Circuit

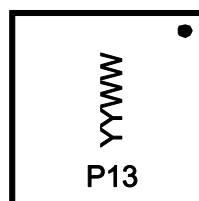
## Ordering Information (Note 4)

Part Number	Case	Packaging
DMP4013LFG-7	POWERDI®3333-8	2,000/Tape & Reel
DMP4013LFG-13	POWERDI®3333-8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information

POWERDI®3333-8



P13= Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Last Digit of Year (ex: 13 = 2013)  
 WW = Week Code (01 ~ 53)

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	$V_{DSS}$	-40	V	
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V	
Continuous Drain Current (Note 6) $V_{GS} = -10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	-10.3 -8.3	A
	$t < 10\text{s}$	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	-13.7 -11	A
Pulsed Drain Current (10 $\mu\text{s}$ pulse, duty cycle = 1%)	$I_{DM}$	80	A	
Maximum Continuous Body Diode Forward Current (Note 6)	$I_S$	2.6	A	
Avalanche Current, $L = 0.1\text{mH}$	$I_{AS}$	34	A	
Avalanche Energy, $L = 0.1\text{mH}$	$E_{AS}$	58	mJ	

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_D$	1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	123	$^\circ\text{C/W}$
	$t < 10\text{s}$	69	
Total Power Dissipation (Note 6)	$P_D$	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	60	$^\circ\text{C/W}$
	$t < 10\text{s}$	34	
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	3.3	$^\circ\text{C}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-40	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	$I_{DSS}$	—	—	-1	$\mu\text{A}$	$V_{DS} = -40\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	-1	—	-3	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	9.4	13	m $\Omega$	$V_{GS} = -10\text{V}, I_D = -10\text{A}$
		—	12.3	18		$V_{GS} = -4.5\text{V}, I_D = -8\text{A}$
Diode Forward Voltage	$V_{SD}$	—	-0.7	-1.2	V	$V_{GS} = 0\text{V}, I_S = -1\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	$C_{iss}$	—	3,426	—	pF	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	$C_{oss}$	—	283	—	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	235	—	pF	
Gate Resistance	$R_g$	—	4.7	—	$\Omega$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ( $V_{GS} = -4.5\text{V}$ )	$Q_g$	—	32.5	—	nC	$V_{DS} = -20\text{V}, I_D = -10\text{A}$
Total Gate Charge ( $V_{GS} = -10\text{V}$ )	$Q_g$	—	68.6	—	nC	
Gate-Source Charge	$Q_{gs}$	—	8.2	—	nC	
Gate-Drain Charge	$Q_{gd}$	—	9.9	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	5.3	—	ns	$V_{DD} = -20\text{V}, V_{GEN} = -10\text{V}, R_G = 3\Omega, I_D = -10\text{A}$
Turn-On Rise Time	$t_r$	—	20	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	126	—	ns	
Turn-Off Fall Time	$t_f$	—	83	—	ns	
Body Diode Reverse Recovery Time	$t_{rr}$	—	19.5	—	nS	$I_F = -10\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	$Q_{rr}$	—	9.8	—	nC	

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
  - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to product testing.

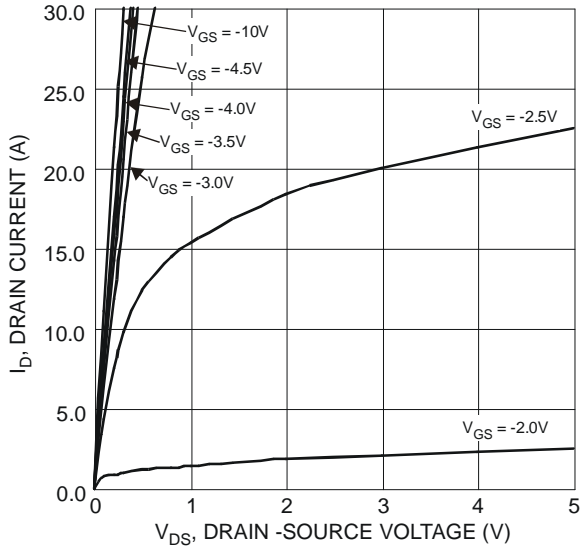


Figure 1 Typical Output Characteristics

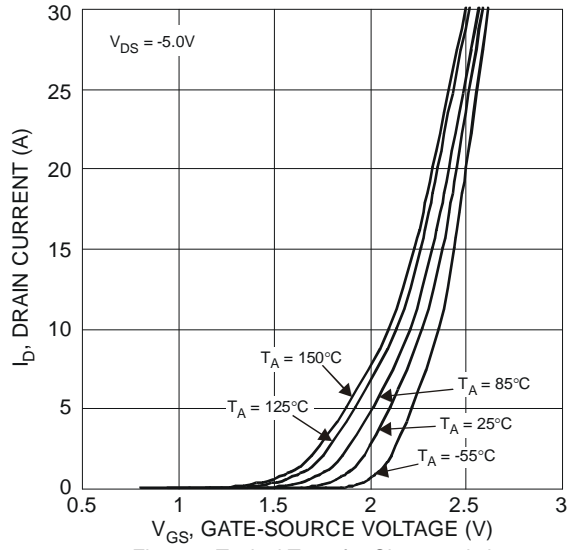


Figure 2 Typical Transfer Characteristics

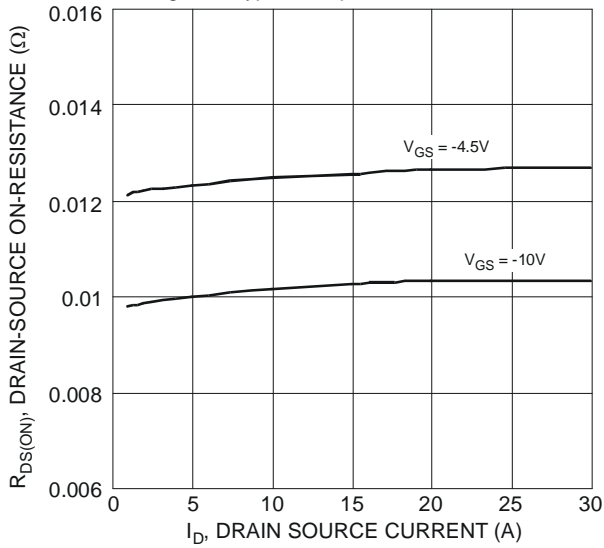


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

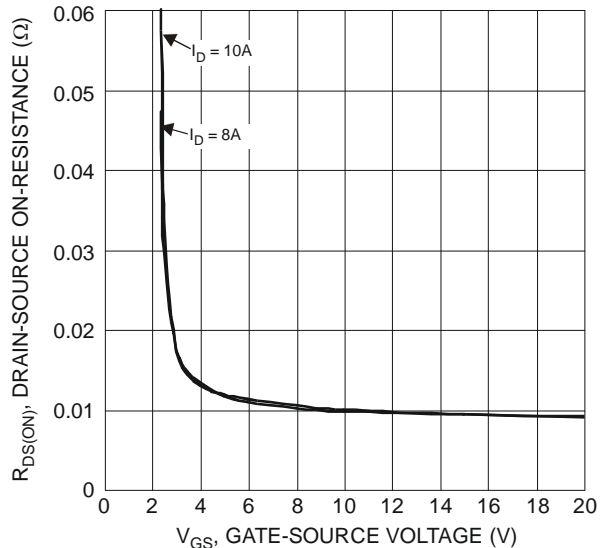


Figure 4 Typical Transfer Characteristics

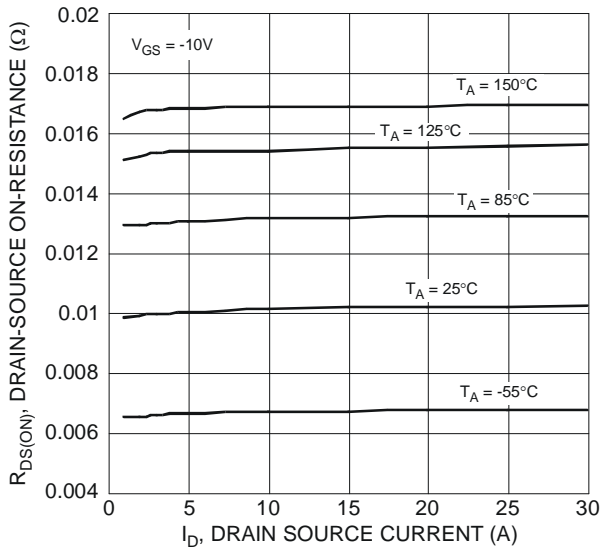


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

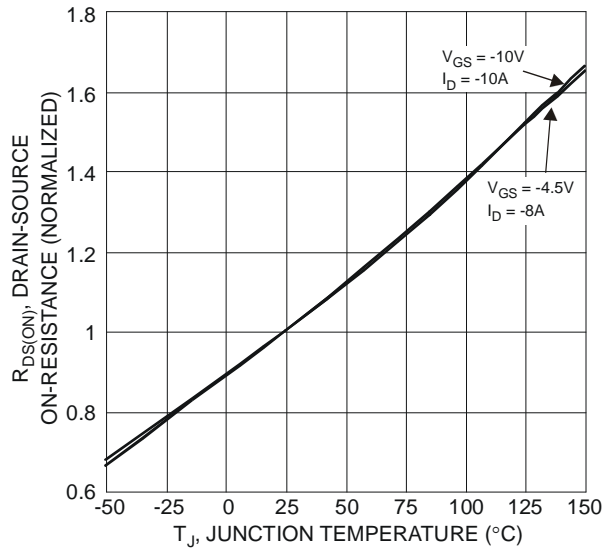


Figure 6 On-Resistance Variation with Temperature

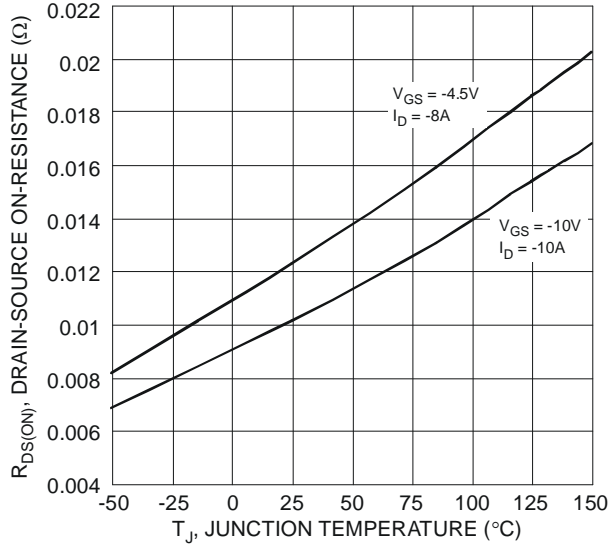


Figure 7 On-Resistance Variation with Temperature

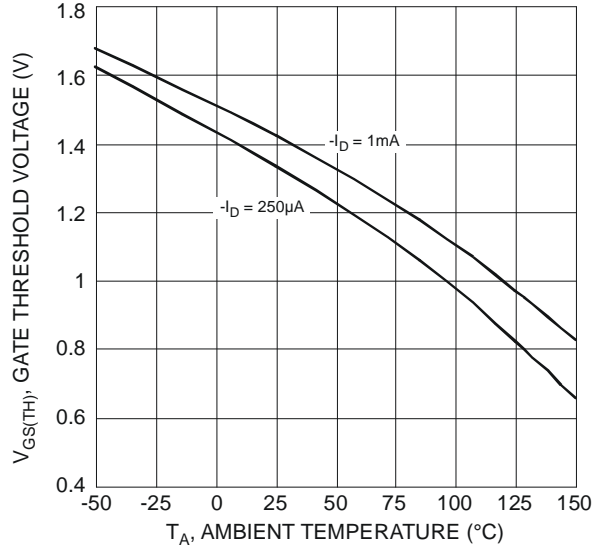


Figure 8 Gate Threshold Variation vs. Ambient Temperature

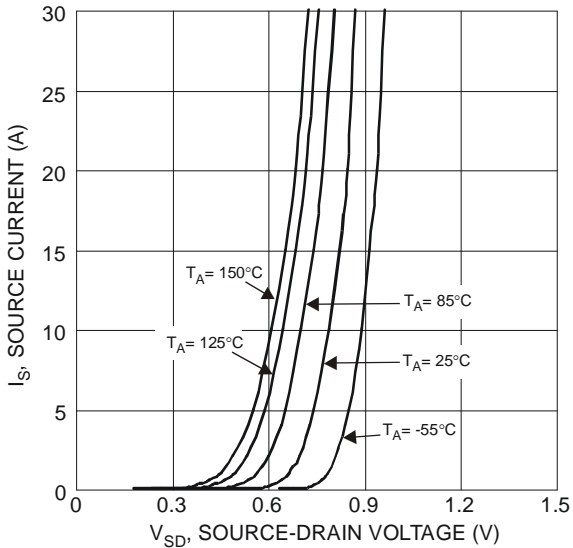


Figure 9 Diode Forward Voltage vs. Current

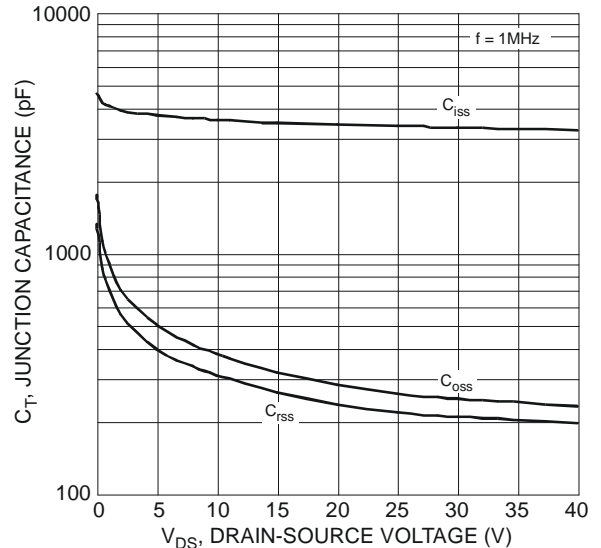


Figure 10 Typical Junction Capacitance

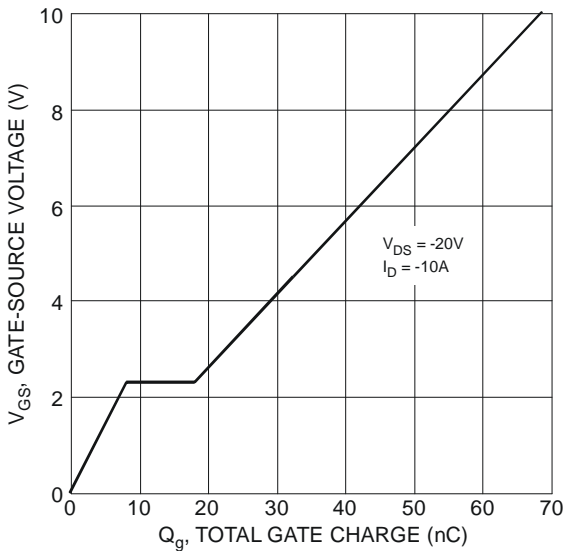


Figure 11 Gate-Charge Characteristics

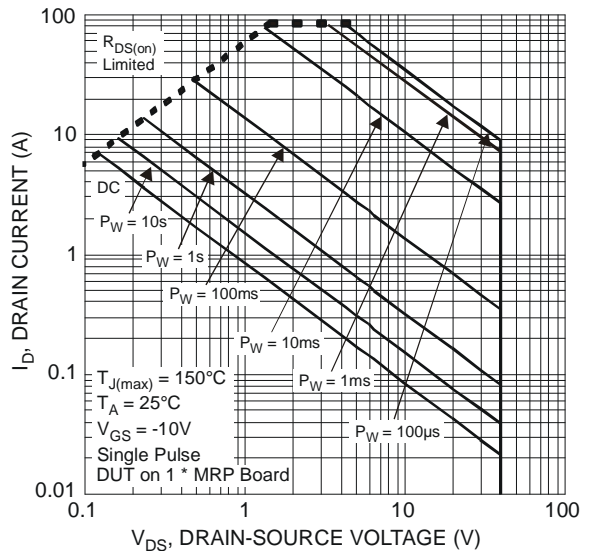
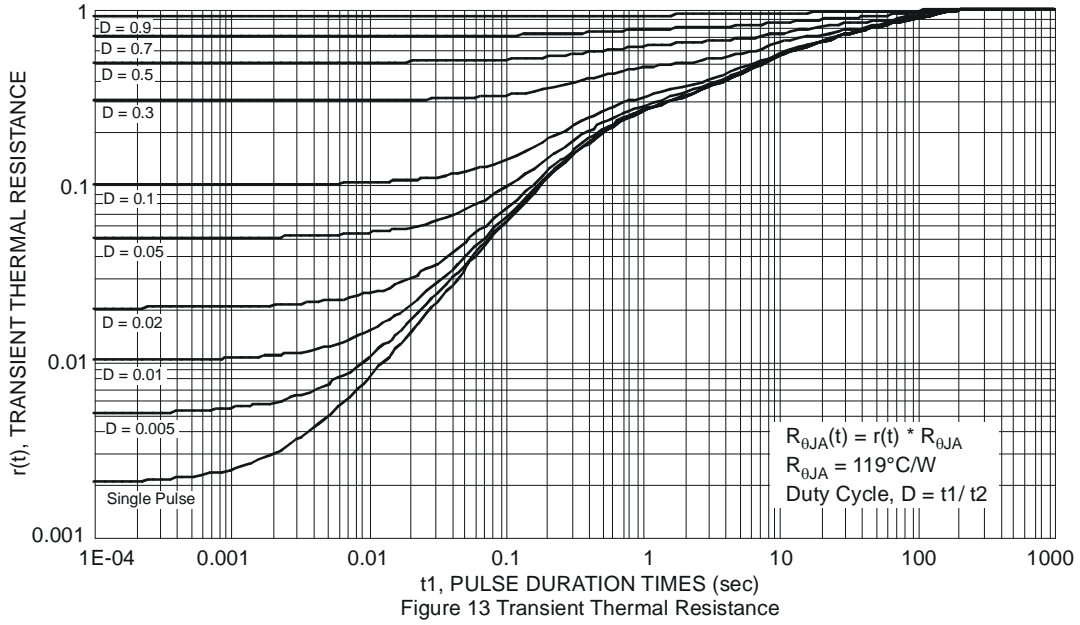


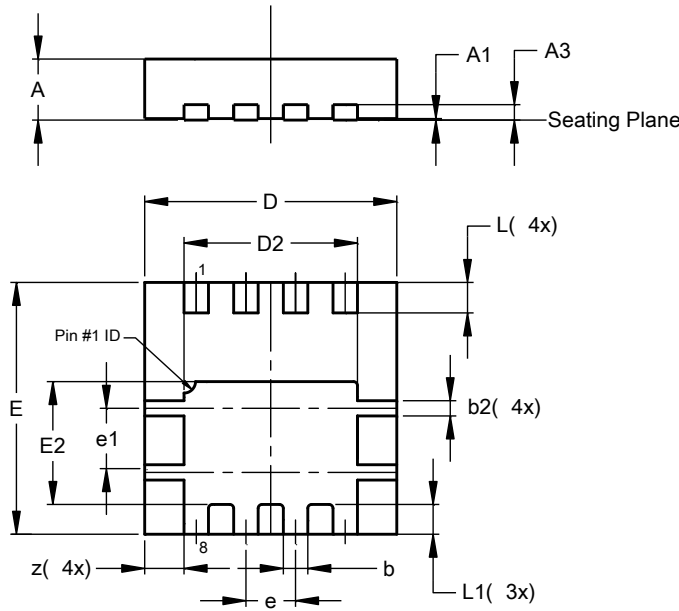
Figure 12 SOA, Safe Operation Area



**Package Outline Dimensions**

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

**POWERDI®3333-8**

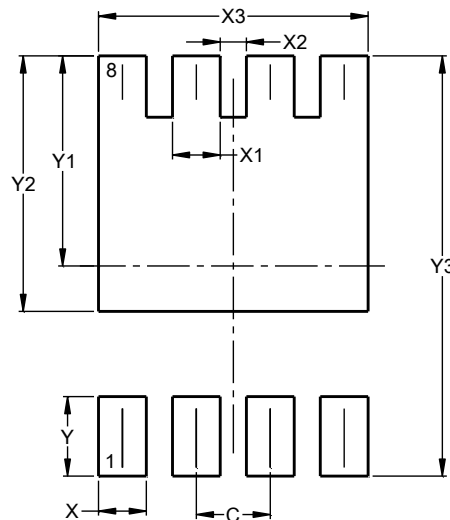


POWERDI®3333-8			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	-	-	0.203
b	0.27	0.37	0.32
b2	-	-	0.20
D	3.25	3.35	3.30
D2	2.22	2.32	2.27
E	3.25	3.35	3.30
E2	1.56	1.66	1.61
e	-	-	0.65
e1	0.79	0.89	0.84
L	0.35	0.45	0.40
L1	-	-	0.39
z	-	-	0.515
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

**POWERDI®3333-8**



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700

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